

ABSTRACT

A method and device for thermal treatment of workpieces or components, in particular for producing a soldered joint between a solder material and
5 at least one component or workpiece which is used as a carrier for said solder material, by melting of the solder material arranged on the solder material carrier, wherein the at least one component is heated in a melt chamber (12) in a process atmosphere which is sealed off from the environment, whereby in a subsequent step the component is cooled in a
10 cooling chamber (13) in a process atmosphere which is sealed off from the environment, and whereby the component is heated and cooled in process chambers (12, 13) which are independent of each other.

15 (Fig. 1)



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